



- ☒ (229) (((leadframe lead adj frame) )
- ☒ (382929) (lead, contact electrode) with insulat\$4
- ☒ (470) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (50223) ((lead contact electrode) with insulat\$4) with cover\$
- ☒ (50) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (7633) (((lead contact electrode) with insulat\$4) with cover\$
- ☒ (7) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (88) (stack\$4 near2 ((microchip micro adj chip chip integrat
- ☒ (43) insulat\$4 near2 cover\$4 near4 exposed adj2 (contact el
- ☒ (828) insulat\$4 near4 exposed adj2 (contact electrode lead)
- ☒ (80) (prevent\$3 reduc\$3 eliminat\$3 minimiz\$3 suppress\$3 de
- ☒ (33) ((microchip micro adj chip chip integrated adj circuit di
- ☒ (3) "06177139"
- ☒ (229) (((leadframe lead adj frame) )

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DBs USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM\_TDB

☒ Plurals

Default operator: OR

☒ Highlight all hit terms initially

(((leadframe lead adj frame)  
) with ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) )  
) with ((encapsula\$3 encapsulation mold\$3 resin)  
) and ((1 adj shaped) near2 ((leadframe lead adj frame lead  
) (((stack\$4 near ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) ))) (stack\$4 near packag\$3)) and (((leadframe lead adj frame) with ((encapsula\$3 encapsulation mold\$3 resin) with ((microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure) ))) and ((offset stagger\$3 shift\$3 zigzag\$4 align\$4 near2 angle pitch oblique\$4 inclin\$4 displac\$3)))

April 2003

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	<input type="checkbox"/>	<input type="checkbox"/>	Inventor Δ	Document ID	Issue Date	Page	Title	Current OR	Current XRef	Ret
1	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Asada, Junichi et al.	US 5665651 A	19970909	13	Process for encapsulating a semiconductor device and lead frame	29/827	257/E21.504; 257/E23.042;	
2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	Fujimoto, Hiroaki et al.	US 6498393 B2	20021224	34	Semiconductor device and method for the fabrication thereof	257/692	257/666; 257/787;	
3	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Honuchi, Michio et al.	US 20020031867 A1	20020314	17	Semiconductor device and process of production of same	438/125		
4	<input checked="" type="checkbox"/>	<input checked="" type="checkbox"/>	Huang, Chien Ping	US 20020027273 A1	20020307	12	Semiconductor package and fabricating method thereof	257/678	438/106	
5	<input type="checkbox"/>	<input type="checkbox"/>		JP 2000077598 A	20000314	7	Lead frame structure of resin sealed semiconductor package e.g. chip size package, has protruding portion of L-shaped lead frame acting as			
6	<input type="checkbox"/>	<input type="checkbox"/>		JP 11340373 A	19991210	3	Thin small sized resin sealed electronic circuit chip has L-shaped metal lead frame with larger shape than chip and is depressed from op.			
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Abe, Shunichi et al.	US 20020105061 A1	20020808	33	Semiconductor device and manufacturing method thereof	257/666		
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	Akizawa, Tetsuo et al.	US 4483441 A	19841120	13	Flat-type semiconductor device and packing thereof	206/716	206/499; 206/718	